
PRODUCT CHANGE NOTICE

**Alternate Manufacturing Sites
for Intersil ZL2005*,
ZL2006*, ZL2008*, ZL2105*,
and ZL6100* Products**

**Refer to:
PCN11018**

Date: February 11, 2011

February 11, 2011

To: Our Valued Intersil Customer

Subject: **Alternate Manufacturing Sites for Intersil ZL2005*, ZL2006*, ZL2008, ZL2105*, and ZL6100* Products** – *Jazz Semiconductor Newport Beach, CA and STATS ChipPAC Malaysia*

This notice is to inform you that Intersil is qualifying the Jazz Semiconductor Newport Beach, CA and STATS ChipPAC Malaysia (SCM) facilities as alternate sites for performing wafer fabrication and package assembly of the listed ZL2005*, ZL2006*, ZL2008, ZL2105*, and ZL6100* products. This action will expand current capabilities and capacities to optimize Intersil's ability to meet customer's delivery requirements. The product and site-specific qualification activities are in progress and scheduled to complete in March 2011.

Products affected:

| | | |
|-------------------|---------------|---------------|
| ZL2005ALNF | ZL2005PALRFT1 | ZL2008EALAFT1 |
| ZL2005ALNFT | ZL2006ALNF | ZL2105ALNF |
| ZL2005ALNFT1 | ZL2006ALNFB | ZL2105ALNFT |
| ZL2005ALNFT1S2568 | ZL2006ALNFT | ZL2105ALNFT1 |
| ZL2005ALPF-03 | ZL2006ALNFT1 | ZL6100ALAF |
| ZL2005ALPFT-03 | ZL2008ALAFT | ZL6100ALAFT |
| ZL2005ALPFTK-03 | ZL2008ALAFT1 | ZL6100ALAFTK |
| ZL2005PALRFT | ZL2008EALAFT | |

The Jazz facility is ISO 9001:2008 and ISO/TS 16949:2002 certified and qualified as a supplier to Intersil for wafer fabrication of BCD35 (Bipolar CMOS DMOS) technology products. The STATS ChipPAC Malaysia (SCM) facility is ISO 9001:2008 and ISO/TS 16949:2009 certified and qualified as a supplier to Intersil for assembly and testing of DFN/QFN packaged products.

There will be no change in the package outline drawing (POD) except for the maximum package height. The maximum package height will change from 0.90mm to 1.00mm with nominal values of 0.85mm and 0.90mm respectively. The 1.00mm maximum aligns with JEDEC POD MO-220 variation V. There will be no change in the moisture sensitivity level (MSL). The qualified material sets and plating combinations are as follows:

| Package Style | Material | Current - Amkor | Proposed - SCM |
|---------------|---------------|-----------------|-------------------|
| 6x6 QFN 36p | Mold Compound | CEL 9220 | Sumitomo EME-G770 |
| | Die Attach | AMK06 | Ablestik A8290 |
| | Lead Finish | Matte Sn Finish | Matte Sn Finish |

The wafer fabrication and assembly qualification plans are designed using JEDEC and other applicable industry standards. A summary of the qualification plan and status of completion is included for reference. The qualification results will be available for review upon completion by request.

Product affected by this change is identifiable via Intersil's internal traceability system. In addition, product assembled at SCM may also be identified by the assembly site code (country of assembly) when marked on the devices. The assembly site code for the SCM facility is "H".

Intersil will take all necessary actions to conform to agreed upon customer requirements and to ensure the continued high quality and reliability of Intersil products being supplied. Customers may expect to receive product manufactured at either the current or the newly qualified sites beginning *ninety* days from the date of this notification or earlier with approval.

If you have concerns with this change notice, Intersil must hear from you promptly. Please contact the nearest Intersil Sales Office or call the Intersil Corporate line at 1-888-468-3774, in the United States, or 1-321-724-7143 outside of the United States.

Regards,

Jon Brewster

Jon Brewster
Intersil Corporation

PCN11018

CC: J. Touvell D. Foster T. Wolter M. Pandola C. Lin

PCN11018 - Reliability Qualification Plan

| Reliability Test | ZL2005 (2.5UM TOP METAL) fab'ed using BCD35 36 LEAD 6X6 QFN at SCM | ZL2006 (2.5UM TOP METAL) fab'ed using BCD35 36 LEAD 6X6 QFN at SCM | ZL2105 (2.5UM TOP METAL) fab'ed using BCD35 36 LEAD 6X6 QFN at SCM | ZL2106 (2.5UM TOP METAL) fab'ed using BCD35 36 LEAD 6X6 QFN at SCM |
|---|--|--|--|---|
| High Temperature Operating Life | NA | SRN100453 Rev 0 0/78 125C 1000hr passed | SRN100432 Rev 0 0/78 125C 1000hr passed | SRN100376 Rev 0 0/78 125C 2000hr passed SRN100376 Rev 1 0/78 125C 2000hr passed SRN100376 Rev 2 0/78 125C 1000hr passed |
| Biased HAST | NA | NA | NA | SRN100376 Rev 4 0/78 130C, 85%RH PRECOND L2 PBFREE 96hr passed |
| Storage Life | NA | NA | NA | SRN100376 Rev 0 0/39 150C BAKE AND REFLOW 2000hr passed SRN100376 Rev 1 0/39 150C BAKE AND REFLOW 2000hr passed SRN100376 Rev 2 0/26 150C BAKE AND REFLOW 2000hr passed |
| Destructive Wire Pull after Storage Life | NA | NA | NA | SRN100376 Rev 0 0/6 passed |
| Bond Pull Integrity | NA | NA | NA | SRN100376 Rev 0 0/5 175C 96hr completed 2010-11-18 passed SRN100376 Rev 1 0/5 175C 96hr completed 2010-11-18 passed SRN100376 Rev 2 0/5 175C 96hr completed 2011-01-19 passed |

| Reliability Test | ZL2005 (2.5UM TOP METAL) fab'ed using BCD35 36 LEAD 6X6 QFN at SCM | ZL2006 (2.5UM TOP METAL) fab'ed using BCD35 36 LEAD 6X6 QFN at SCM | ZL2105 (2.5UM TOP METAL) fab'ed using BCD35 36 LEAD 6X6 QFN at SCM | ZL2106 (2.5UM TOP METAL) fab'ed using BCD35 36 LEAD 6X6 QFN at SCM |
|--|---|---|---|---|
| Moisture Sensitivity Classification | MRT10173 MSL=2@260C (Pb Free) Approved=Yes | MRT10176 MSL=2@260C (Pb Free) Approved=Yes | MRT10174 MSL=2@260C (Pb Free) Approved=Yes | MRT10140 MSL=2@260C (Pb Free) Approved=Yes |
| Unbiased HAST | SRN100431 Rev 0 0/81 130C, 85%RH PRECOND L2 PBFREE 96hr passed | SRN100453 Rev 0 0/81 130C, 85%RH PRECOND L2 PBFREE 96hr passed | SRN100432 Rev 0 0/81 130C, 85%RH PRECOND L2 PBFREE 96hr passed | SRN100376 Rev 0 0/39 130C, 85%RH PRECOND L2 PBFREE 96hr passed SRN100376 Rev 1 0/39 130C, 85%RH PRECOND L2 PBFREE 96hr passed SRN100376 Rev 2 0/26 130C, 85%RH PRECOND L2 PBFREE 96hr passed |
| Temperature Cycle | SRN100431 Rev 0 0/81 -65C TO 150C PRECOND L2 PBFREE 500cy passed | SRN100453 Rev 0 0/81 -65C TO 150C PRECOND L2 PBFREE 500cy passed | SRN100432 Rev 0 0/81 -65C TO 150C PRECOND L2 PBFREE 500cy passed | SRN100376 Rev 0 0/39 -65C TO 150C PRECOND L2 PBFREE 500cy passed SRN100376 Rev 1 0/39 -65C TO 150C PRECOND L2 PBFREE 500cy passed SRN100376 Rev 2 0/26 -65C TO 150C PRECOND L2 PBFREE 500cy passed |
| Destructive Wire Pull after Temp Cycle | NA | NA | NA | SRN100376 Rev 0 0/6 passed |
| Product Electrical Characterization | Performed by Product Engineering | Performed by Product Engineering | Performed by Product Engineering | Performed by Product Engineering |
| Statistical Bin Yield Analysis | Performed by Product Engineering | Performed by Product Engineering | Performed by Product Engineering | Performed by Product Engineering |
| ESD Characterization | HBM 2000V MM 200V CDM 750V | HBM 2000V MM 200V CDM 750V | HBM 2000V MM 200V CDM 750V | HBM 2000V MM 200V CDM 750V |
| Latch-up Characterization | Passed Class II, LevelA @ 85C | Passed Class II, LevelA @ 85C | Passed Class II, LevelA @ 85C | Passed Class II, LevelA @ 85C |